



**AAEON Technology INC.**  
ISO-9001/ISO-14001 Certified  
Industrial Automation PCs

# **PCM-6897 rev:A02**

## **Thermal Image Analysis Report**

**Release Date: Apr . 30, 2003**

**04-30-2003**

**Issue Stamp**

**Wayne Chang**

**DV Manager**

**Rex Chang**

**Test Engineer**

# Thermal Image Analysis

---

. **Model Name:** PCM-6897 Rev.A0.2 (BIOS:0.2)

. **Description:** Compact Board.

. **Date:** Apr. 30, 2003

. **Measure Site:** AAEON DV Dept.

. **Issued by :** Rex Chang

.**Equipment:** TVS-100 series by NIPPON AVIONICS CO., LTD.

. **Simulation Environment:**

**Temperature:** Component Side : 23.8 degrees C

**CPU:** Pentium 850MHz

**RAM:** 128MB SDRAM NEC D45128841G5-A75-9JF(PC-133 SDRAM)

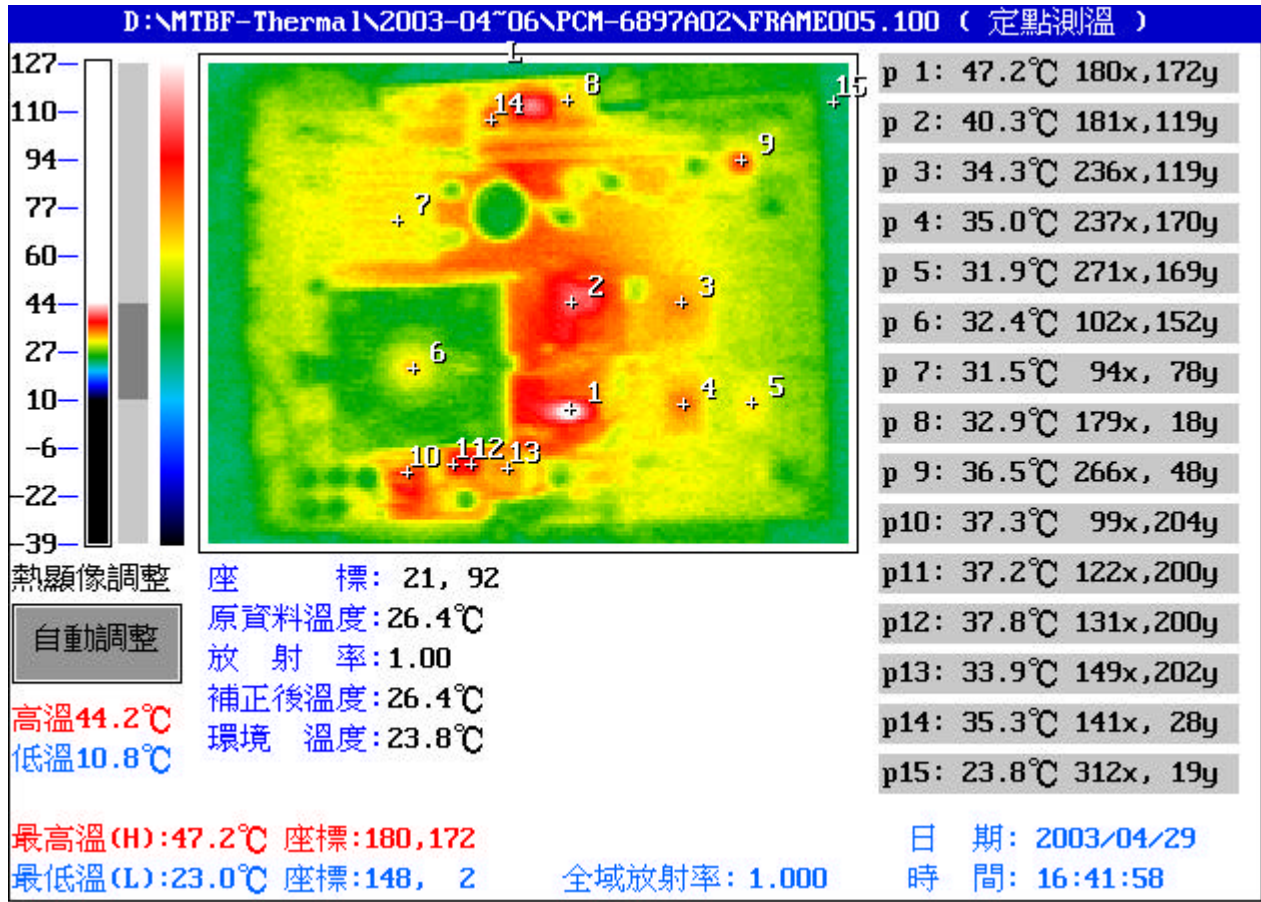
**Hardware:** PQI Compact Flash 32MB

**Application Software:** QAPLus 5.5

**Take Picture Time:** Power on 30 minutes after

# Temperature Profile Test:

Component Side:



Picture 1

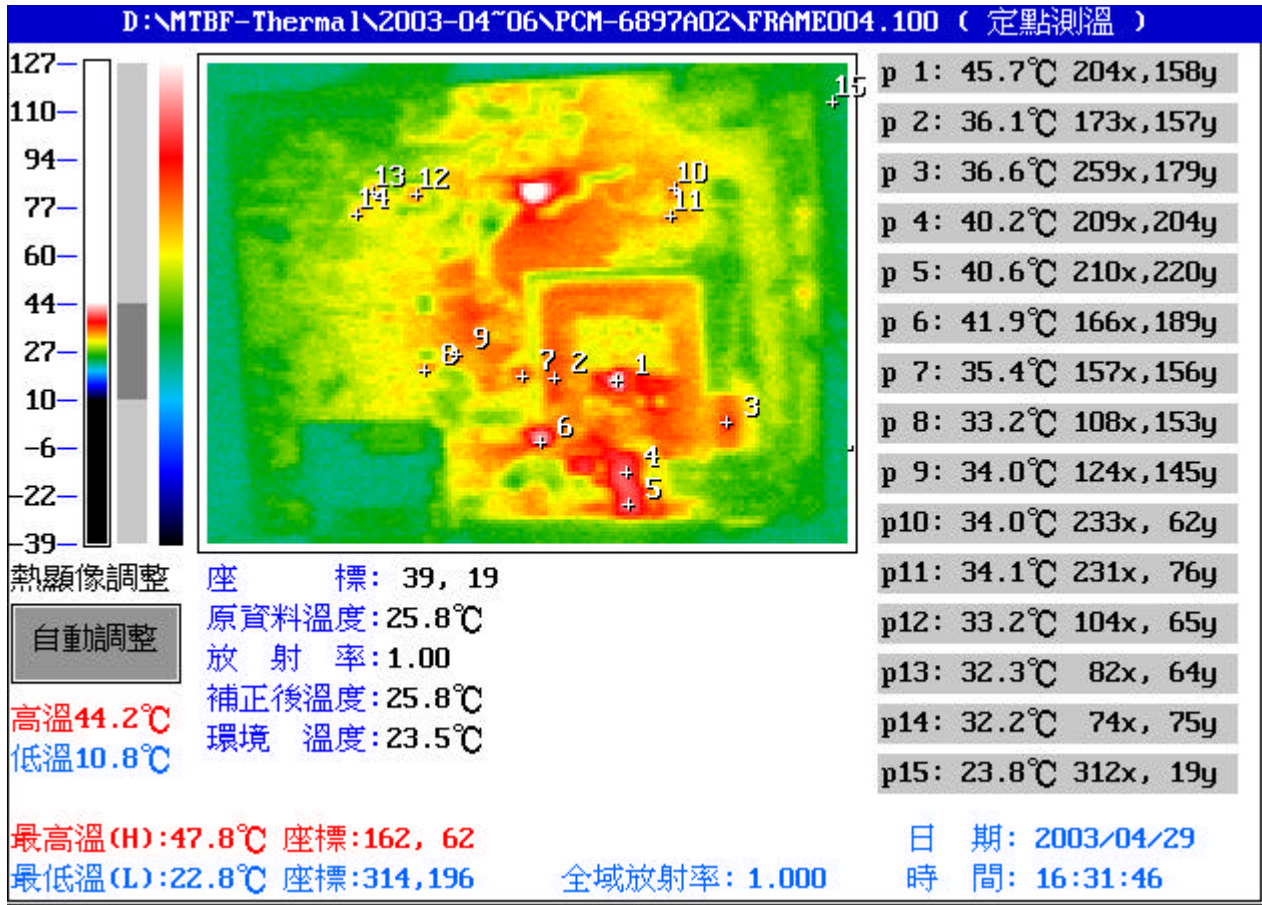
Point	Position	Describe	Ts	Tm	Note
1	U2	IC.SMD.SSOP 56Pin Clock Generator.ICS.94201DF-995		47.2	
2	U31	IC.SMD BGA 316Pin.Display Controller W/4M RAM.SMLSM722G4		40.3	
3	U4	IC.SMD.Chipset ICH2 B5.INTEL.FW82801BA SL5WK		34.3	
4	U32	IC.SMD.IT8712F 128P Super I/O.ITE.IT8712F/GX		35.0	
5	U10	IC.SMD.IT8712F 128P Super I/O.ITE.IT8712F/GX		31.9	
6	U1	ZIF SKT.DIP.370P CIRCLE.(SOCKET 370).鴻海.PZ37041-S01-A		32.4	
7	U3	IC.SMD.Chipset 815E B-Step.INTEL.FW82815 SL5NQ		31.5	
8	U34	IC.SMD.SSOP48 Chipset.INTEL.DA82562ET		32.9	
9	U8	IC.SMD.AC'97 Audio Codec.AVANCE LOGIC.ALC201		36.5	
10	L4	COIL.2uH.DIP Wire Size1.0mm.18 材 3wire*6.5TS 20~30Amp.高創.C6018-10C06YDP		37.3	
11	TC10	SP CAP.150uF.6.3V.20%.D(7.3*4.3*4.2mm).150hm SMD.Panasonic.EEFUE0J151R		37.2	
12	TC11	SP CAP.150uF.6.3V.20%.D(7.3*4.3*4.2mm).150hm SMD.Panasonic.EEFUE0J151R		37.8	
13	L3	COIL.1uH.DIP Wire Size 1.0mm.18 材 3wire*4.5TS 20~30Amp.高創.C5018B-10C04YDP		33.9	
14	U22	REG.SMD SOT223.1A Linear Regulator.UNISEM.US1010CY		35.3	
15		The Room Temperature		23.8	

1. Operation Temperature ( ):

Ts = Defined by component specification ; Tm = Measured by DV

# Temperature Profile Test:

Solder Side:



Picture 2

Point	Position	Describe	Ts	Tm	Note
1	U26	REG.SMD SOT223.1A Linear Regulator.UNISEM.US1010CY		45.7	
2	U1	ZIF SKT.DIP.370P CIRCLE.(SOCKET 370).鴻海.PZ37041-S01-A		36.1	
3	U25	IC.SMD.SOIC 28Pin PWM Controller.Intersil.ISL6524CB		36.6	
4	Q19	PWR.SMD.TO-263AB N-Channel PowerMosfet.Intersil.HUF76137S3S		40.2	
5	Q18	PWR.SMD.TO-263AB N-Channel PowerMosfet.Intersil.HUF76137S3S		40.6	
6	Q17	PWR.SMD.TO-252AA N-Channel PowerMosfet.Intersil.HUF76107D3ST		41.9	
7	C393	SP CAP.150uF.6.3V.20%.D(7.3*4.3*4.2mm).15Ohm SMD.Panasonic.EEFUE0J151R		35.4	
8	Q24	REG.SMD SOT223.1A Linear Regulator.UNISEM.US1010CY		33.2	
9	TC26	SP CAP.150uF.6.3V.20%.D(7.3*4.3*4.2mm).15Ohm SMD.Panasonic.EEFUE0J151R		34.0	
10	Q20	PWR.SMD.TO-252AA N-Channel PowerMosfet.Intersil.HUF76107D3ST		34.0	
11	TC17	SP CAP.150uF.6.3V.20%.D(7.3*4.3*4.2mm).15Ohm SMD.Panasonic.EEFUE0J151R		34.1	
12	Q15	PWR.SMD.TO-252AA N-Channel PowerMosfet.Intersil.HUF76107D3ST		32.2	
13	Q14	PWR.SMD.TO-252AA N-Channel PowerMosfet.Intersil.HUF76107D3ST		32.3	
14	U12	IC.SMD SOP.8Pin Switching PWM Controller.IR.IRU3037CS		32.2	
15		The Room Temperature		23.8	

1. Operation Temperature ( ):

Ts = Defined by component specification ; Tm = Measured by DV